

INFORMATION DISCLOSURE CITATION

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Application Number

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Applicant(s)

Kevin Petrarca, et al.

Filing Date

09/30/04

Group Art Unit

2818

U.S. PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (# known)			
THN	AA**	US-5,484,518	01/1996	GOLDBERG	
THN	AB**	US-6,261,433	07/2001	LANDAU	
THN	AC**	US-6,331,237	12/2001	ANDRICACUS et al.	
THN	AD**	US-6,113,771	09-05-2000	LANDAU et al.	

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T*
		Country Code ³ -Number ⁴ -Kind Code ⁵ (# known)				
THN	BA**	EP-0952242	11-16-1998	LANDAU, et al.		

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. **CITE NO.: Those patent(s) or publication(s) which are marked with an double asterisk (**) next to the Cite No. are not supplied because they were previously cited by or submitted to the Office in a prior application relied upon in this application for an earlier filing date under 35 U.S.C. 120. ³ Applicant's unique citation designation number (optional). ² See Kind Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T*
THN	CA**	A Novel Electrolyte Composition for Copper Plating in Wafer Metallization, Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc. Proceedings Volume 99-9.	
THN	CB**	A Model of Superfilling in Damascene Electroplating, H. DELIGIANI, et al.; The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	
THN	CC**	Model of Wafer Thickness Uniformity in an Electroplating Tool, The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	
THN	CD**	A Model of Superfilling in Damascene Electroplating, H. DELIGIANI, et al.; Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.: Uziel LANDAU, et al., The Electrochemical Society, Inc., Proceedings Volume 99-9.	
THN	CE**	Uziel LANDAU, A Novel Electrolyte Composition for Copper Plating in Wafer Metallization, Abstract No. 263.	
THN	CF**	Model of Wafer Thickness Uniformity in an Electroplating Tool, Electrochemical Processing in ULSI Fabrication and Semiconductor/Metal Deposition II: Proceedings of the International Symposium; P.C.H. DELIGIANI, et al., The Electrochemical Society, Inc., Proceedings Volume 99-9.	
THN	CG**	Computational Aspects of the Terminal Effect on Wafer-Scale Uniformity, H. DELIGIANI et al.; The 195 th Meeting of Electrochemical Society, Inc. Meeting Abstracts, Volume 99-1 (May 2-6, 1999).	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. **CITE NO.: Those patent(s) or publication(s) which are marked with an double asterisk (**) next to the Cite No. are not supplied because they were previously cited by or submitted to the Office in a prior application relied upon in this application for an earlier filing date under 35 U.S.C. 120.

Examiner Signature	<i>[Signature]</i>	Date Considered	07/06/06
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